



(0.80 mm) .0315"

RU8-160-25-SE-L-DV-BL

HSC8-050-02-19-DP

RU8, HSC8 SERIES

# HIGH SPEED RISER CARD KIT

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?RU8](http://www.samtec.com?RU8)

### Connector:

Insulator Material:

Black LCP

Contact: BeCu

Plating:

Au or Sn over

50µ" (1.27 µm) Ni

Current Rating:

3.1 A per pin

(6 adjacent pins powered)

Operating Temp:

-55°C to +125°C

### Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (40-60)

RoHS Compliant: Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



**Note:** While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

**Note:** Some lengths, styles and options are non-standard, non-returnable.



## RU8 1 POSITIONS PER ROW STACK HEIGHT SIGNAL ROUTING PLATING OPTION DV BL OTHER OPTION

40, 50, 60

-19

= (19 mm) .748"

-25

= (25 mm) .984"

-30

= (30 mm) 1.180"

-SE

= Single-Ended

-DP

= Differential Pair

-L

= 10µ" (0.25 µm)

Gold on contact,

Matte Tin on tail

(Plating for

connectors)

Plating for Card

is Hard Gold

-BL

= Board

Locks

(Bottom

Socket only)

(Not available

on -19 stack

height)

Leave blank for Trays

-K

= (5.50 mm)

.217" DIA

Polyimide

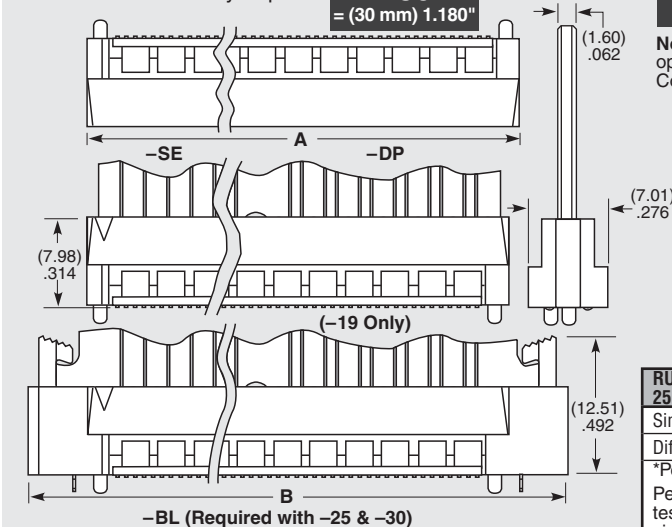
Film Pick &amp;

Place Pad

-TR

= Tape &amp; Reel

Kit contains two connectors and one card. Assembly required.



**Note:** Other Gold plating options available. Contact Samtec.

NO. OF POSITIONS PER SIDE	A	B	-SE TOTAL SIGNAL LINES	-DP TOTAL SIGNAL PAIRS
40	(39.80) 1.567	(51.05) 2.010	40	26
50	(47.80) 1.882	(59.05) 2.325	50	32
60	(55.80) 2.197	(67.05) 2.640	60	38

**Finalinch**  
CERTIFIED

RU8 25 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	7.5 GHz / 15 Gbps
Differential Pair Signaling	7.5 GHz / 15 Gbps

\*Performance data includes effects of a non-optimized PCB. Performance data for other stack heights and complete test data available at [www.samtec.com?RU8](http://www.samtec.com?RU8) or contact [sig@samtec.com](mailto:sig@samtec.com)

Mates with:

HSEC8

## SPECIFICATIONS

For complete specifications see [www.samtec.com?HSC8](http://www.samtec.com?HSC8)

### Conductor:

1/2 oz Copper

Contact Area:

Hard Gold Plated

Insulator: FR-4

RoHS Compliant: Yes

## HSC8 NUMBER OF POSITIONS PER SIDE CARD STYLE STACK HEIGHT SIGNAL ROUTING

-040, -050, -060

-02

= (1.60 mm)

.062"

thick card

-19

= (19 mm)

.748"

-25

= (25 mm)

.984"

-30

= (30 mm)

1.180"

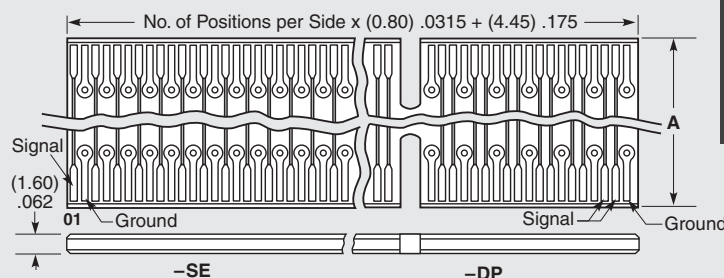
-SE

= Single-Ended

-DP

= Differential Pair

NO. OF POSITIONS PER SIDE	-SE TOTAL SIGNAL LINES	-DP TOTAL SIGNAL PAIRS
-040	40	26
-050	50	32
-060	60	38



STACK HEIGHT	A
-19	(14.84) .584
-25	(20.84) .820
-30	(25.84) 1.017

**Note:** Some sizes, styles and options are non-standard, non-returnable.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

Due to technical progress, all designs, specifications and components are subject to change without notice.